

**IN THE UNITED STATES PATENT & TRADEMARK OFFICE**

Appln. Ser. No.:	Filed:	Inventor(s):	Atty Dkt:
Divisional of 09/825,418	3 April 2000	Y. Awakura	114GI-135A
Title: Wiring Board Comprising Granular Magnetic Film			

Asst. Comm'r for Patents  
Washington, D.C. 20231-0001

**PRELIMINARY AMENDMENT**

Dear Sir:

Prior to an examination on the merits of the subject application, please first amend the application as follows, the amendments being shown in marked-up form in the attached appendix.

**IN THE SPECIFICATION:**

Page 1, after the title and prior to the background section, add the paragraph:

This application is a divisional of application 09/825,418, filed 3 April 2001, a Convention application based on Japanese applications 101756 and 101765, both filed 4 April 2000.

**IN THE CLAIMS:**

1. (Amended.) A wiring board, comprising:  
an insulative base material;  
conductor patterns formed thereon;  
magnetic thin films formed on at least one of said conductor patterns;  
and  
said magnetic thin films being formed with an insulation layer  
interposed therebetween, that covers the entirety of the  
surface of said wiring board on which said conductor patterns  
are formed.

Cancel claim 3.